

后芮驷(上海)电子有限公司

Horus International Electronics Co., LTD.



SPECIFICATION FOR APPROVAL

品名DESCRIPTION:SMD Type Power Coupled Inductor规格SPEC :HRS-RCA-C1040-100M包装PACKAGE:卷装客户CUSTOMER:_______

客户料号 CUSTOMER P/N:

| APPROVED BY | | |
|-------------|--|--|
| | 王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王王 | |
| CUSTOMER | HORUS | |

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编号:





SMD Type Power Coupled Inductor

P/N: RCA- C1040-100M



Moisture Sensitivity Level: 1

Content in this sheet are subject to change without prior notice



1. Dimension (mm):



- C: Inductance 100=10uH
- D: Inductance Tolerance M= \pm 20%

| 3.Electrical Characteristics: | | | | | | | | | |
|-------------------------------|---------------------------------|---|------|----------------|---------------------|----------------|-----------------------------|----------|----------|
| Part Number | Inductance(uH) @0.25v/500KHz | $L_{1-2} DCR(m \Omega) L_{3-4} DCR(m \Omega)$ | | L_{1-2} Isat | $L_{^{1-2}} \ Irms$ | L_{3-4} Isat | $L_{^{3-\!4}} \text{ Irms}$ | | |
| | | Max. | Тур. | Max. | Тур. | (A) Typ. | (A) Typ. | (A) Typ. | (A) Typ. |
| RCA-C1040-100M | 10 | 65.8 | 97 | 77.5 | 92 | 6.9 | 4.5 | 8.3 | 4.3 |





4.Reliabllity and Test Condition:

| Item | Performance | Test Condition | | | |
|--|---|---|--|--|--|
| Operating temperature | -55~+150 $^{\circ}$ C (Including self - temperature rise) | | | | |
| Storage temperature and Humidity range | 110~+40℃,50~60%RH (Product with taping) 255~+150℃ (on board) | | | | |
| Electrical Performance | Test | | | | |
| Inductance | Refer to standard electrical characteristics | HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter. | | | |
| DCR | list. | CH16502,Agilent33420A Micro-Ohm Meter. | | | |
| Saturation Current (Isat) | Approximately △L30% | Saturation DC Current (Isat) will cause L0 to drop △L(%) | | | |
| Heat Rated Current (Irms) | Approximately △T40°C | Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(C)$. 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer | | | |
| Reliability Test | | | | | |
| High Temperature Exposure (Storage) AEC-Q200 | | Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020DClassification Reflow Profiles Temperature : 150±2°C (Inductor) Duration : 1000hrs Min. Measured at room temperature after placing for 24±2 hrs. | | | |
| Temperature Cycling AEC-Q200 | | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1 : -55±2°C 30min Min.(Inductor) Step2 : 150±2°C transition time 1min MAX. Step3 : 150±2°C 30min Min. Step4 : Low temp. Transition time 1min MAX. Number of cycles : 1000 Measured at room temperature after placing for 24±2 hrs. | | | |
| Moisture Resistance | Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value | Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020DClassification Reflow Profiles 1.Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2.Raise temperature to $65\pm2°C$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to $25°C$ in 2.5hrs. 3.Raise temperature to $65\pm2°C$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to $25°C$ in 2.5hrs,keep at $25°C$ for 2hrs then keep at -10°C for 3hrs 4.Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs. | | | |
| Biased Humidity (AEC-Q200) | | Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity : 85±3% R.H, Temperature : 85°C±2°C Duration: 1000hrs Min with 100% rated current. Measured at room temperature after placing for24±2hrs | | | |
| High Temperature Operational Life (AEC-Q200) | | Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020DClassification Reflow Profiles Temperature : 150±2°C (Inductor) Duration : 1000hrs Min. With 100% rated current. Measured at room temperature after placing for24±2hrs | | | |
| External Visual | Appearance : No damage. | Inspect device construction, marking and workmanship. Electrical Test not required. | | | |
| Physical Dimension | According to the product specification size measurement | According to the product specification size measurement | | | |
| Resistance to Solvents | Appearance : No damage. | Add aqueous wash chemical - OKEM clean or equivalent. | | | |
| Mechanical Shock | Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value | Type Peak value (g's) Normal Duration (D) (ms) Wave form Velocity Change (Vi)ft/sec SMD 100 6 Half-sine 12.3 Lead 100 6 Half-sine 12.3 Shocks in each direction along 3 perpendicular axes. 100 100 100 | | | |



| Item | Performance | Test Condition | | | |
|---------------------------------|---|--|--|--|--|
| Vibration | | IPC/JEDEC J-STD-020DClassification Reflow Profiles Oscillation Frequency: 10~2K~10Hz for 20 minute Equipment : Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations) ° | | | |
| Resistance to Soldering Heat | Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not | Test condition : Temperature () Time(s) Temperature ramp/immersion And emersion rate Number of heat cycles 260±5(solder temp) 10±1 25mm/s ±6 mm/s 1 | | | |
| Thermal shock (AEC-Q200) | exceed the specification value | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1 : -55±2°C 15±1min(Inductor) Step2 : 150±2°C vithin 20Sec. Step3 : 150±2°C 15±1min Number of cycles : 300 Measured at room temperature after placing fo24±2hrs | | | |
| ESD | Appearance:No damage. | 10 to the second | | | |
| Solder ability | More than 95% of the terminal electrode should be covered with solder \circ | Steam Aging: 8 hours ± 15 min Preheat: 150 , 60sec. Solder: Sn96.5% Ag3% Cu0. 5% Temperature: 245±5 | | | |
| Electrical Characterization | Refer Specification for Approval | Summary to show Min, Max, Mean and Standard deviation. | | | |
| Flammability | Electrical Test not required. | V-0 or V-1 are acceptable. | | | |
| Board Flex | Appearance : No damage | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down. The apparatus shall consist of mechanical means to apply a force which will bend the board (D) $x = 2$ mm minimum. The duration of the applied forces shall be 60 (+ 5) sec. The force is to be applied only once to the board. | | | |
| | | Probe to exert bending force | | | |
| Terminal Strength (SMD) | Appearance : No damage | Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a 17.7 N (1.8 Kg) force to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. | | | |



5.Soldering and Mounting:

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools. Note. If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk

(2) Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1.

(3) Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.







(4) Recommend PC Board Pattern(mm)





6.Package Information:

Packaging Quantity: 800pcs/Reel

(1) Reel Dimension:



| Туре | A(mm) | B(mm) | C(mm) | D(mm) |
|----------|-----------|-------|-------------|-------|
| 13"x16mm | 24.4+2/-0 | 100±2 | 13+0.5/-0.2 | 330 |

(2) Tape Dimension:



User direction of feed

(3) Tearing Off Force:



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 standard).

Application Notice

Storage Conditions To maintain the solder ability of terminal electrodes:

- 1. RDM products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: -10~ 40 $^{\circ}\mathrm{C}$ and 30~70% RH.
- 3. Recommended products should be used within 6 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- · Transportation1.Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

| Modify | recor | ds: |
|---------|-------|-------------|
| Version | Page | Description |
| V01 | N/A | New issued |